

(0,80mm) .0315"

MEC8-RA, MEC8-EM SERIES

# RIGHT ANGLE/EDGE MOUNT SOCKETS

Mates with:  
(1,60mm) .062" thick cards,  
EEDP

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?MEC8-RA](http://www.samtec.com?MEC8-RA)

**Insulator Material:** Black LCP  
**Contact Material:** Phosphor Bronze

**Plating:** Au or Sn over 50µ" (1,27µm) Ni

**Operating Temp Range:** -55°C to +125°C

**Insertion Depth:** (3,94mm) .155" to (6,25mm) .246"

**Current Rating:** 1.8A @ 30°C Temperature Rise

**Voltage Rating:** 265 VAC

**RoHS Compliant:** Yes

**Lead-Free Solderable:** Yes

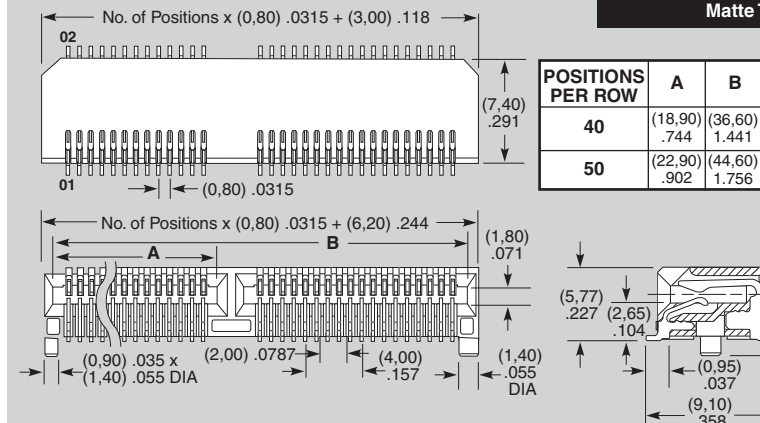
**Note:** Some sizes, styles and options are non-standard, non-returnable.

MEC8 - 1 POSITIONS PER ROW - 02 PLATING OPTION - D - RA1 - OTHER OPTION

10, 13, 20, 25, 30, 37, 40, 49, 50

-L  
= 10µ" (0,25µm) Gold on contact, Matte Tin on tail

-TR  
= Tape & Reel Packaging



POSITIONS PER ROW	A	B
40	(18,90) .744	(36,60) 1.441
50	(22,90) .902	(44,60) 1.756

0,80mm MEC8-RA	Rated @ 3dB Insertion Loss
5,78mm Stack Height	
Single-Ended Signaling	6.5 GHz / 13 Gbps
Differential Pair Signaling	8.0 GHz / 16 Gbps

For complete test data go to [www.samtec.com?MEC8-RA](http://www.samtec.com?MEC8-RA) or contact [sig@samtec.com](mailto:sig@samtec.com)

**APPLICATION SPECIFIC OPTION**

- 1mm mating card thickness option
- Latching option (mates with EEDP series)

Call Samtec.

Mates with:  
(1,60mm) .062" thick cards

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?MEC8-EM](http://www.samtec.com?MEC8-EM)

**Insulator Material:** Black LCP  
**Contact Material:** Phosphor Bronze

**Plating:** Au or Sn over 50µ" (1,27µm) Ni

**Operating Temp Range:** -55°C to +125°C

**Insertion Depth:** (4,32mm) .170" to (5,66mm) .223"

**Current Rating:** 1.8A @ 30°C Temperature Rise

**Voltage Rating:** 265 VAC

**RoHS Compliant:** Yes

**Lead-Free Solderable:** Yes

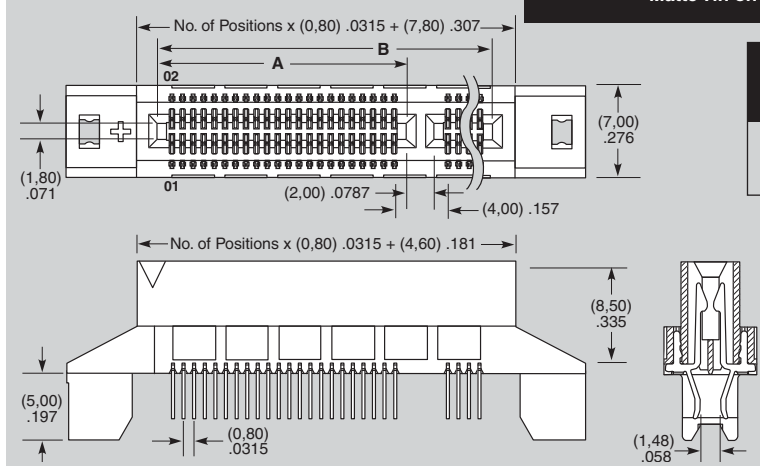
**Note:** Some sizes, styles and options are non-standard, non-returnable.

MEC8 - 1 POSITIONS PER ROW - 02 PLATING OPTION - D - -EM2

10, 20, 30, 40, 50, 60, 70

-L  
= 10µ" (0,25µm) Gold on contact, Matte Tin on tail

-EM2  
= (1,60mm) .062" thick PCB



POSITIONS PER ROW	A	B
40	(18,90) .744	(36,60) 1.441
50	(22,90) .902	(44,60) 1.756
60	(26,90) 1.059	(52,60) 2.071
70	(30,90) 1.217	(60,60) 2.386

**APPLICATION SPECIFIC OPTION**

1mm mating card thickness option.  
Call Samtec.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM